



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED SIZE	PLATED	QTY
A	12.0	PLATED	464
B	31.5	PLATED	15
C	35.43	PLATED	36
D	43.31	PLATED	14
E	51.0	PLATED	2
F	55.0	PLATED	5
G	59.05	PLATED	4
H	82.68	PLATED	2
I	35.43	NON-PLATED	2
L	125.98	NON-PLATED	6
TOTAL HOLES:			550

SLOT HOLES: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	FINISHED SIZE	PLATED	QTY
	787.4x43.3	NON-PLATED	4

TOTAL HOLES: 4

Finished Hole Tolerance - All units are in Inches -			
Finish Hole Diameter	Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter	
0.008" - 0.013"	+0.002 / - 0.002	+/- 0.002	
0.014" - 0.063"	+/- 0.003	+/- 0.002	
0.064" - 0.156"	+/- 0.004	+/- 0.003	
0.157" - 0.250"	+/- 0.007	+/- 0.004	
0.251" and up	+/- 0.007	+/- 0.005	
0.125"	Non Plated Only	+0.003 / - 0.000"	

REVISION DATE

Description		Symbol	
DRILLING AND PROFILING		STSPIN32F0601Q	
I&PC, AMS Group		Group	
ALL RIGHTS STRICTLY RESERVED. REPRODUCTION OR ISSUE TO THIRD PARTIES IN ANY FORM WHATEVER IS NOT PERMITTED WITHOUT WRITTEN AUTHORIZATION FROM STMicronics.		EVSPI32F06Q1S3	
TOLERANCE UNLESS NOTED		ISO	
UNIT=MM		SCALE: 1 : 1	
linear		ANG. LES.	
0 <10 >10		Material	
<10 <50 >200		Treatment and surface finishing	
midle		±0.1 ±0.2 ±0.3 ±0.5 ±1°	
accurate		±0.05 ±0.1 ±0.15 ±0.25 ±30°	

FABRICATION NOTE:

- 1:FABRICATE USING LATEST REVISION OF IPC-6012A CLASS 2 OR ABOVE
- 2:FABRICATE USING MASTER ARTWORK EVSPIN32F0601S3 R1 FOR CIRCUIT PATTERN NO DEVIATION FROM MASTER ARTWORK ARE PERMITTED WITHOUT WRITTE APPROVAL FROM AN AUTHORIZED STMicronics REPRESENTATIVE
- 3:VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK, LOT OR JOB NUMBER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4:MATERIAL: FR4 RoHS COMPLIANT MINIMUM 170 C (High Tg)
- 5:SEE "DETAIL 'A'" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 6:GREEN SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE SOLDERMASK
- 6:FINISH: HAL Lead Free
- 7:FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED
- 8:SILKSCREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9:THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10:DESIGNATED AREA OR INSPECTION AND TEST STAMP
- 11:ON BOTTOM PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE (MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 12:VENDOR TO PROVIDE BOARD STACK-UP FOR IMPEDANCE APPROVAL PRIOR TO BOARD FABRICATION..STACK UP AND IMPEDANCE TO INCLUDE COPPER PLATING ON OUTER LAYERS..FAB DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY VENDOR TO PROVIDE BOARD FOR IMPEDANCE TEST RESULTS AND COUPON TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 13:TEARDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION
- 14:REMOVE SILKSCREEN FROM SOLDERABLE SURFACE
- 15:ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON SHORTS, APPLY TEST STAMP IN REFERENCED AREA
- 16:THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

DETAIL 'A'

LAYER BUILD UP
(reference only)

Cu - 70u
CORE - 1500u
Cu - 70u

(external Cu th are after plating)
estimated total thickness 1640u